Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP 100B All-in-One PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>10</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>9</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>4</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td>0</td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

| Components and waste containing asbestos | 0 |
| Components, parts and materials containing refractory ceramic fibers | 0 |
| Components, parts and materials containing radioactive substances | 0 |

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. 
2. 
3. 
4. 
5. 
6. 
7. 
8. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Mechanical parts disassembly

1) Put the unit on a platform and let the stand upside.

2) Unlock the screw as the photo shows

3) Disassemble the rear cover of the machine
4) Unlock the 2 screws on the iron.

![Unlocking screws on iron](image1)

5) Unlock the screw of the cover.

![Unlocking cover screw](image2)

6) Disassemble the foot as photo show.

![Disassembling foot](image3)
7) Disassemble the speaker

8) Disassemble the base pan and front bezel

9) Disassemble the panel from the unit
10) Unlock the 2 screws in vertical directions

11) Unlock the 3 screws and take the H/S out.

12) Pull the cable out.
13) Disassemble the inverter board

14) Unlock the screw

15) Disassemble the WL module
16) Pull the HDD cable and inverter cable out

17) Disassemble it on basepan

18) Take the DDR cover off
19) Take the ODD off from the unit

20) Take the MB off from the unit

21) Tear antenna off
22) Tear side IO label off from the base pan
Figure 2: CCFLs Remove from Panel

Step 1: Unfix the Screw (3 Point) Remove the cover shield

Step 2: Dismantle the case top (down)

Step 3: Dismantle the case top (Left/right)

Step 4: Separate case top (push the case top because of damages on COF)

Step 5: Separate board ass'y

Step 6: Separate wires from the tape (2 Point)

Step 7: Pull lamp housing with tool & hands (+Be careful not to break the Lamp)

Step 8: Pull lamp housing with hands normal to LCD

Step 9: Separated lamp ass'y (UP)
Figure 3: Remove Battery from MB.

Step 1: Clip the battery nap.

Step 2: Remove the battery.